

3.5x2.8 mm SMD CHIP LED LAMP

Part Number: AA3529ZG24ZS

PRELIMINARY SPEC



OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



Features

- Single color.
- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- Ideal for backlighting.
- White SMD package, silicone resin.
- Low thermal resistance.
- Package: 1500pcs / reel.
- Moisture sensitivity level : level 2a.
- RoHS compliant.

Description

The Green source color devices are made with InGaAIN Vertical Light Emitting Diode.

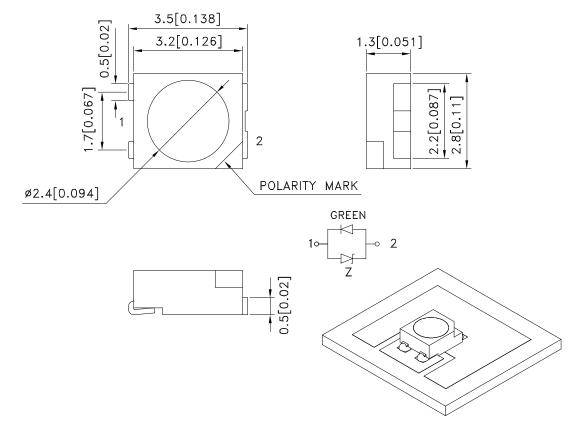
GREEN

Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.4. The device has a single mounting surface. The device must be mounted according to the specifications.





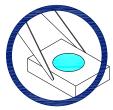
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Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

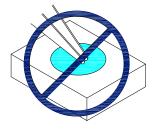
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might leads to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

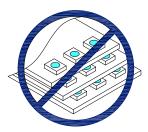


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

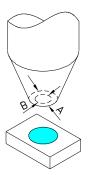




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
- 5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 150mA		Фv (mlm) [2] @ 150mA		Viewing Angle [1]
			Min.	Тур.	Min.	Тур.	2 θ 1/2
AA3529ZG24ZS	GREEN (InGaAIN)	WATER CLEAR	6700	7500	18000	21000	120°

Notes

1.0 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2.Luminous Intensity/ Luminous Flux: +/-15%

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Value	Unit
Power Dissipation	Pt	585	mW
Junction Temperature [1]	TJ	110	°C
Operating Temperature	Тор	-40 To +85	°C
Storage Temperature	Tstg	-40 To +85	°C
DC Forward Current [1]	lF	150	mA
Peak Forward Current [2]	Iғм	350	mA
Thermal Resistance [1] (Junction/ambient)	Rth j-a	170	°C/W
Thermal Resistance [1] Junction/solder point) Rth j-S 50		50	°C/W
Electrostatic Discharge Threshold (HBM)	8000	V	

Notes

Electrical / Optical Characteristics at Ta=25°C

Parameter	Symbol	Value	Unit	
Wavelength at peak emission Ir=150mA [Typ.]	λ peak	515	nm	
Dominant Wavelength IF=150mA [Typ.]	λ dom [1]	525	nm	
Spectral Line Half-width IF=150mA [Typ.]	Δλ	30	nm	
Forward Voltage IF=150mA [Min.]		2.9		
Forward Voltage IF=150mA [Typ.]	VF [2]	3.4	V	
Forward Voltage Ir=150mA [Max.]		3.9		
Temperature coefficient of λ peak IF=150mA, -10 $^{\circ}$ C \leq T \leq 100 $^{\circ}$ C [Typ.]	TC λ peak	0.09	nm/° C	
Temperature coefficient of λ dom IF=150mA, -10 $^{\circ}$ C \leq T \leq 100 $^{\circ}$ C [Typ.]	TC λ dom	0.03	nm/° C	
Temperature coefficient of VF IF=150mA, -10 $^{\circ}$ C \leq T \leq 100 $^{\circ}$ C [Typ.]	TCv	-2.7	mV/° C	

Notes

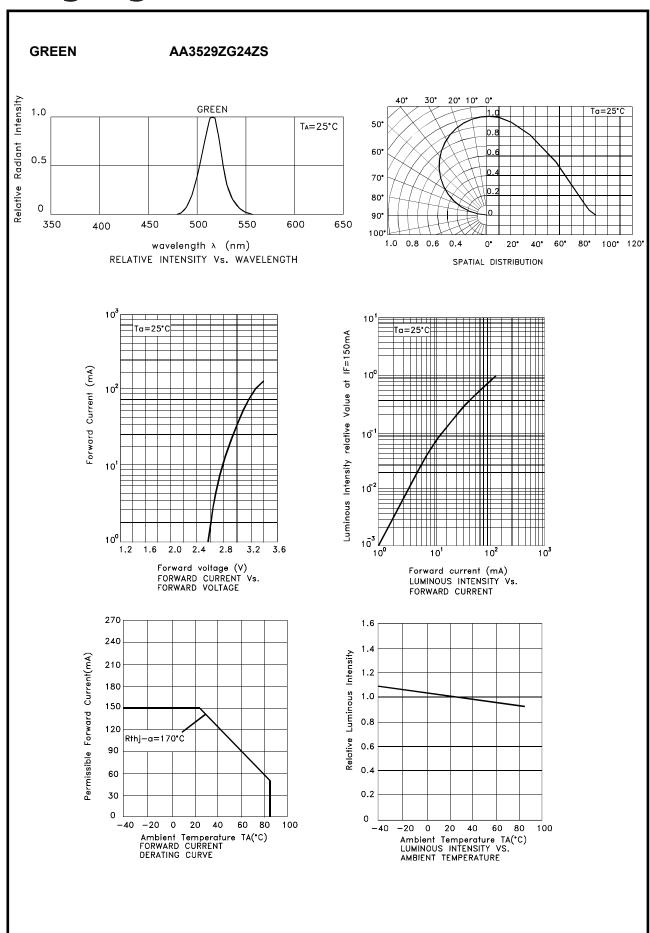
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^{1.}Results from mounting on PC board FR4(pad size ≥ 70mm²), mounted on pc board-metal core PCB is recommend for lowest thermal Resistance.

^{2.1/10} Duty Cycle, 0.1ms Pulse Width.

^{1.}Wavelength: +/-1nm.

^{2.} Forward Voltage: +/-0.1V.

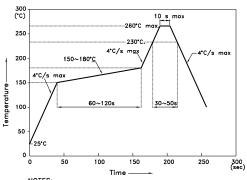


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Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

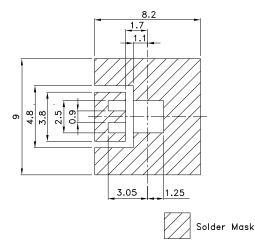
1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

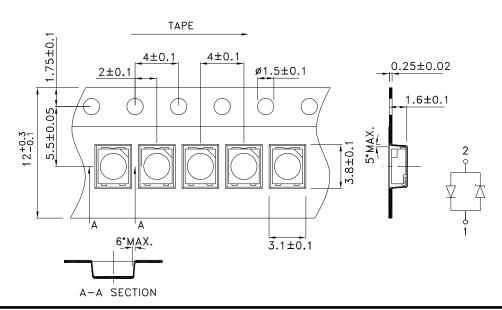
3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern

(Units: mm; Tolerance: ± 0.1)



Tape Specifications (Units: mm)

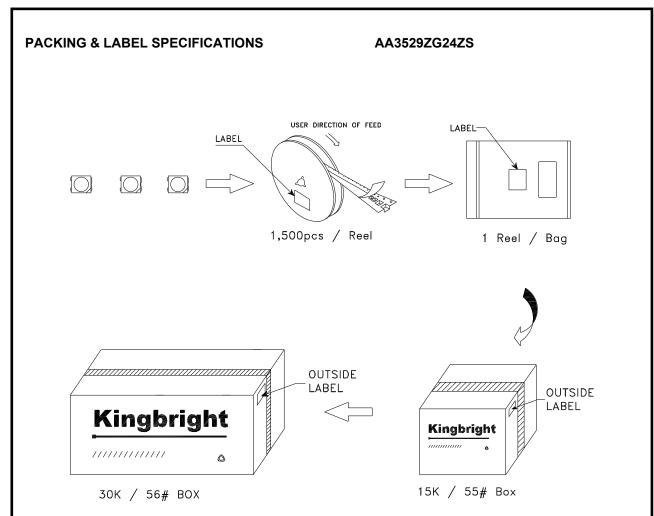


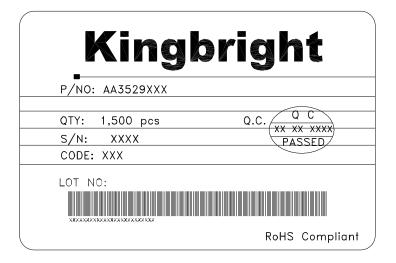
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